

Title (en)

CERAMIC AND/OR POWDER-METALLURGICAL COMPOSITE SHAPED BODY AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

KERAMISCHER UND/ODER PULVERMETALLURGISCHER VERBUNDFORMKÖRPER UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)

CORPS MOULÉ COMPOSITE EN CÉRAMIQUE ET/OU DE LA MÉTALLURGIE DES POUDRES ET PROCÉDÉ D'UTILISATION DUDIT CORPS

Publication

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Application

**EP 08701277 A 20080107**

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Abstract (en)

[origin: WO2008087064A2] The invention relates to the field of ceramics and to composite shaped bodies that can be used, for example, for chip removing tools. The aim of the invention is to provide composite shaped bodies that have a free structure on their top surface and delimiting surface and that can be produced in series. Said aim is achieved in that the ceramic and/or powder-metallurgical composite shaped bodies are made of a green sheet and an injection moulded body. Said aim is further achieved, according to the invention, in that a green sheet is incorporated into or applied to a mould, subsequently, at least one ceramic and/or powder-metallurgical injection moulding mass is applied to and/or placed on and/or incorporated on and/or in the mould by means of injection moulding, and subsequently, the mould having one or several parts is removed and/or the one or multi-part composite shaped bodies are removed from the mould. The steps according to the invention can be repeated one or several times.

IPC 8 full level

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